

Title (en)
FORMULATION COMPRISING A P-TYPE ORGANIC SEMICONDUCTOR MATERIAL AND AN N-TYPE SEMICONDUCTOR MATERIAL

Title (de)
FORMULIERUNG AUS EINEM ORGANISCHEN HALBLEITERMATERIAL VOM TYP P UND EINEM HALBLEITERMATERIAL VOM TYP N

Title (fr)
FORMULATION COMPRENANT UN MATERIAU SEMICONDUCTEUR ORGANIQUE DE TYPE P ET UN MATERIAU SEMICONDUCTEUR DE TYPE N

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Application
EP 20733629 A 20200622

Priority
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• EP 2020067381 W 20200622

Abstract (en)
[origin: WO2020260214A1] The present description relates to a formulation comprising a p-type organic semiconductor polymer comprising a conjugated aryl compound, a conjugated heteroaryl compound or a mixture of two or more of these compounds; an n-type semiconductor material comprising fullerene, substituted fullerene or a mixture of two or more of these compounds; and a non-aqueous solvent, wherein the concentration of the p-type organic semiconductor polymer is 4 mg/mL to 8 mg/mL per milliliter of solvent, and the concentration of the n-type organic semiconductor material is 10 mg/mL to 14 mg/mL per milliliter of solvent.

IPC 8 full level
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